Storage
Since printed wiring boards absorb moisture in the environment, pay attention to the following points when storing them:
① Keep in a moisture-proof package (polyethylene bag and silica gel) until using them.
② Store in an air-conditioned room (below 25°C and below 60%RH).
③ Do not leave boards in a non-air-conditioned room (humidity: over 60%RH) before mounting.
④ When using only some of the boards, keep the remaining ones in the same moisture-proof package in which they were delivered.
⑤ Even when kept in a moisture-proof package, these boards will gradually absorb moisture in the environment during humid seasons. When storing them for more than three months, take care to keep them dry.

Drying
When boards are assumed to have absorbed moisture because of improper storage conditions or long-term storage of more than three months, be sure to dry them before use.
① Recommended drying conditions:

<table>
<thead>
<tr>
<th>Drying temperature (°C)</th>
<th>Drying time (hrs.)</th>
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</thead>
<tbody>
<tr>
<td>80</td>
<td>24</td>
</tr>
<tr>
<td>100</td>
<td>12</td>
</tr>
<tr>
<td>130</td>
<td>2</td>
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</tbody>
</table>

② Hold the boards horizontally during drying.
③ Too high drying temperature (over 130°C) may cause oxidization of copper foil and discoloration of boards.
④ In case of devices are mounted on boards, dry the boards at temperature at which the heat resistance of the part is taken into account. This applies to boards with surface protection coating.
⑤ After drying, component mounting as soon as possible. If the work does not proceed smoothly, protect these boards with a moisture-proof package.

Heating
① Note that excessive force on the board during heating may cause bow, twist or measling.
② During high temperature heat treatment (such as fusing), rapid heating and cooling may result in interlayer cracks, board swellings, and/or other defects. Such heating or cooling should be done step-by-step. To improve reliability, be sure to dry the materials before heat treatment.

Soldering
The solder heat resistance of MCL is greatly affected by the temperature of the solder bath. So, use an L-shaped thermometer to control carefully the temperature of the solder bath. When using a soldering iron, note that the actual temperature at the tip varies on its manufacturer and structure even though soldering irons are of the same capacity. You are recommended to measure the temperature with a surface thermometer in advance and to use the soldering iron below 300°C. After soldering, try not to move the substrates while the soldered portions remain hot.
Measling and blistering of the glass fabric epoxy MCLs are apt to occur on wet printed wiring boards. So dry them (at 130°C for 1 to 2 hours) before soldering. Excessively hot solder may result in shorter heat-resistance time, leading to swellings in circuits and boards. Make sure to maintain the appropriate temperature.